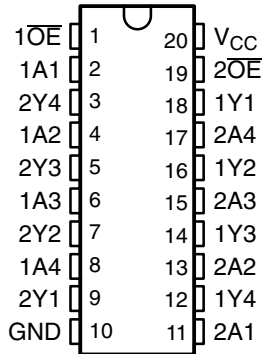


# SN54LVTH244A, SN74LVTH244A 3.3-V ABT OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

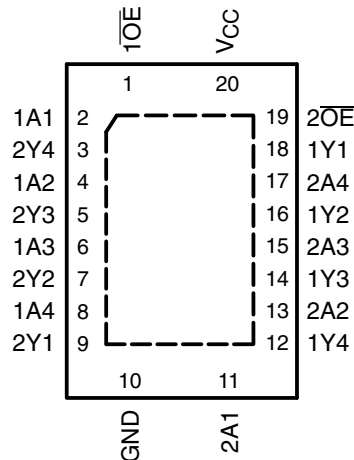
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- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V  $V_{CC}$ )
- Typical  $V_{OLP}$  (Output Ground Bounce)  $<0.8$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Support Unregulated Battery Operation Down to 2.7 V
- $I_{off}$  and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

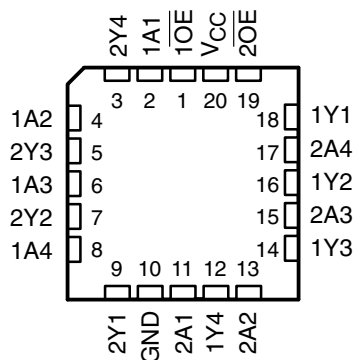
SN54LVTH244A . . . J OR W PACKAGE  
SN74LVTH244A . . . DB, DW, NS,  
OR PW PACKAGE  
(TOP VIEW)



SN74LVTH244A . . . RGY PACKAGE  
(TOP VIEW)



SN54LVTH244A . . . FK PACKAGE  
(TOP VIEW)



## description/ordering information

These octal buffers and line drivers are designed specifically for low-voltage (3.3-V)  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74LVTH244ARGYR	LXH244A
	SOIC – DW	Tube	SN74LVTH244ADW	LVTH244A
		Tape and reel	SN74LVTH244ADWR	
	SOP – NS	Tape and reel	SN74LVTH244ANSR	LVTH244A
	SSOP – DB	Tape and reel	SN74LVTH244ADBR	LXH244A
	TSSOP – PW	Tape and reel	SN74LVTH244APWR	LXH244A
	VFBGA – GQN	Tape and reel	SN74LVTH244AGQNR	LXH244A
–55°C to 125°C	VFBGA – ZQN (Pb-free)		SN74LVTH244AZQNR	
	CDIP – J	Tube	SNJ54LVTH244AJ	SNJ54LVTH244AJ
	CFP – W	Tube	SNJ54LVTH244AW	SNJ54LVTH244AW
	LCCC – FK	Tube	SNJ54LVTH244AFK	SNJ54LVTH244AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54LVTH244A, SN74LVTH244A  
3.3-V ABT OCTAL BUFFERS/DRIVERS  
WITH 3-STATE OUTPUTS

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description/ordering information (continued)

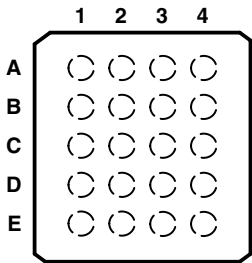
The 'LVTH244A devices are organized as two 4-bit line drivers with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the devices pass data from the A inputs to the Y outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

These devices are fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

SN74LVTH244A . . . GQN OR ZQN PACKAGE  
(TOP VIEW)



terminal assignments

	1	2	3	4
A	1A1	1 $\overline{OE}$	$V_{CC}$	2 $\overline{OE}$
B	1A2	2A4	2Y4	1Y1
C	1A3	2Y3	2A3	1Y2
D	1A4	2A2	2Y2	1Y3
E	GND	2Y1	2A1	1Y4

FUNCTION TABLE  
(each buffer)

INPUTS		OUTPUT Y
$\overline{OE}$	A	
L	H	H
L	L	L
H	X	Z

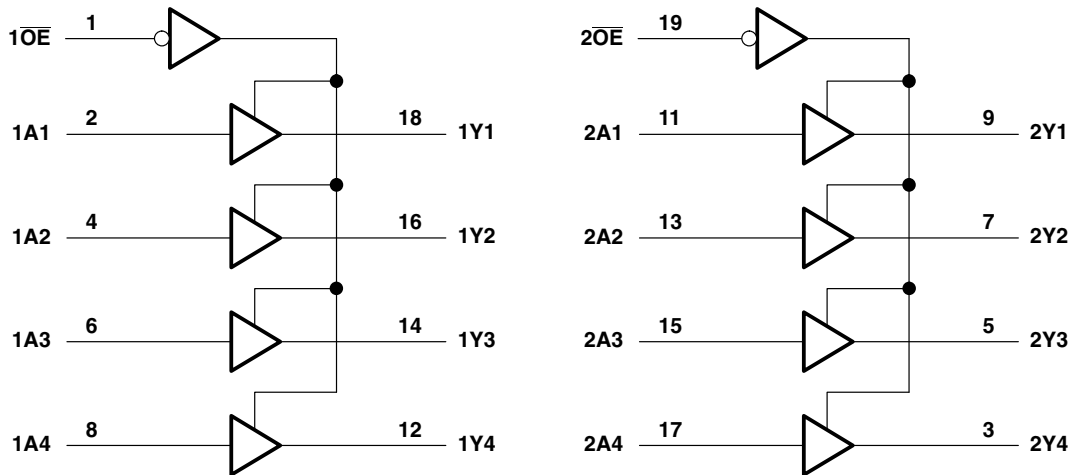
# SN54LVTH244A, SN74LVTH244A

## 3.3-V ABT OCTAL BUFFERS/DRIVERS

### WITH 3-STATE OUTPUTS

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#### logic diagram (positive logic)



Pin numbers shown are for the DB, DW, FK, J, NS, PW, RGY, and W packages.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	–0.5 V to 4.6 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, $V_O$ (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, $I_O$ : SN54LVTH244A	96 mA
SN74LVTH244A	128 mA
Current into any output in the high state, $I_O$ (see Note 2): SN54LVTH244A	48 mA
SN74LVTH244A	64 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): DB package	70°C/W
(see Note 3): DW package	58°C/W
(see Note 3): GQN/ZQN package	78°C/W
(see Note 3): NS package	60°C/W
(see Note 3): PW package	83°C/W
(see Note 4): RGY package	37°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .
  3. The package thermal impedance is calculated in accordance with JESD 51-7.
  4. The package thermal impedance is calculated in accordance with JESD 51-5.

# SN54LVTH244A, SN74LVTH244A

## 3.3-V ABT OCTAL BUFFERS/DRIVERS

### WITH 3-STATE OUTPUTS

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#### recommended operating conditions (see Note 5)

			SN54LVTH244A		SN74LVTH244A		UNIT
			MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage		2.7	3.6	2.7	3.6	V
V <sub>IH</sub>	High-level input voltage		2		2		V
V <sub>IL</sub>	Low-level input voltage			0.8		0.8	V
V <sub>I</sub>	Input voltage			5.5		5.5	V
I <sub>OH</sub>	High-level output current			–24		–32	mA
I <sub>OL</sub>	Low-level output current			48		64	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate		200		200		μs/V
T <sub>A</sub>	Operating free-air temperature		–55	125	–40	85	°C

NOTE 5: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN54LVTH244A, SN74LVTH244A

## 3.3-V ABT OCTAL BUFFERS/DRIVERS

### WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54LVTH244A		SN74LVTH244A		UNIT
				MIN	TYP†	MAX	MIN	
V <sub>IK</sub>		V <sub>CC</sub> = 2.7 V, I <sub>I</sub> = −18 mA		−1.2		−1.2		V
V <sub>OH</sub>		V <sub>CC</sub> = 2.7 V to 3.6 V, I <sub>OH</sub> = −100 μA		V <sub>CC</sub> −0.2		V <sub>CC</sub> −0.2		V
		V <sub>CC</sub> = 2.7 V, I <sub>OH</sub> = −8 mA		2.4		2.4		
		V <sub>CC</sub> = 3 V	I <sub>OH</sub> = −24 mA	2				
			I <sub>OH</sub> = −32 mA			2		
V <sub>OL</sub>		V <sub>CC</sub> = 2.7 V	I <sub>OL</sub> = 100 μA	0.2		0.2		V
			I <sub>OL</sub> = 24 mA	0.5		0.5		
		V <sub>CC</sub> = 3 V	I <sub>OL</sub> = 16 mA	0.4		0.4		
			I <sub>OL</sub> = 32 mA	0.5		0.5		
			I <sub>OL</sub> = 48 mA	0.55				
			I <sub>OL</sub> = 64 mA			0.55		
I <sub>I</sub>	Control inputs	V <sub>CC</sub> = 0 or 3.6 V, V <sub>I</sub> = 5.5 V		50		10		μA
		V <sub>CC</sub> = 3.6 V, V <sub>I</sub> = V <sub>CC</sub> or GND		±1		±1		
	Data inputs	V <sub>CC</sub> = 3.6 V	V <sub>I</sub> = V <sub>CC</sub>	1		1		
			V <sub>I</sub> = 0	−5		−5		
I <sub>off</sub>		V <sub>CC</sub> = 0, V <sub>I</sub> or V <sub>O</sub> = 0 to 4.5 V				±100		μA
I <sub>I(hold)</sub>	Data inputs	V <sub>CC</sub> = 3 V	V <sub>I</sub> = 0.8 V	75		75		μA
			V <sub>I</sub> = 2 V	−75		−75		
		V <sub>CC</sub> = 3.6 V‡, V <sub>I</sub> = 0 to 3.6 V				500 −750		
I <sub>OZH</sub>		V <sub>CC</sub> = 3.6 V, V <sub>O</sub> = 3 V		5		5		μA
I <sub>OZL</sub>		V <sub>CC</sub> = 3.6 V, V <sub>O</sub> = 0.5 V		−5		−5		μA
I <sub>OZPU</sub>		V <sub>CC</sub> = 0 to 1.5 V, V <sub>O</sub> = 0.5 V to 3 V, OE = don't care		±100*		±100		μA
I <sub>OZPD</sub>		V <sub>CC</sub> = 1.5 V to 0, V <sub>O</sub> = 0.5 V to 3 V, OE = don't care		±100*		±100		μA
I <sub>CC</sub>		V <sub>CC</sub> = 3.6 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND	Outputs high	0.39		0.19		mA
			Outputs low	14		5		
			Outputs disabled	0.39		0.19		
ΔI <sub>CC</sub> §		V <sub>CC</sub> = 3 V to 3.6 V, One input at V <sub>CC</sub> − 0.6 V, Other inputs at V <sub>CC</sub> or GND		0.2		0.2		mA
C <sub>i</sub>		V <sub>I</sub> = 3 V or 0		3		3		pF
C <sub>o</sub>		V <sub>O</sub> = 3 V or 0		7		7		pF

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.



# SN54LVTH244A, SN74LVTH244A

## 3.3-V ABT OCTAL BUFFERS/DRIVERS

### WITH 3-STATE OUTPUTS

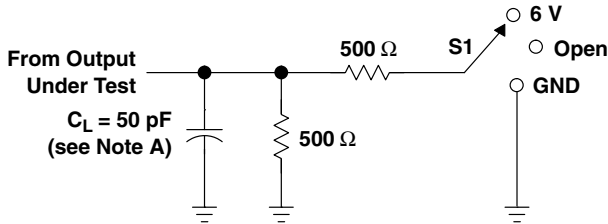
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switching characteristics over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVTH244A				SN74LVTH244A				UNIT	
			V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V			V <sub>CC</sub> = 2.7 V		
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN		MAX
t <sub>PLH</sub>	A	Y	0.5	3.8	4.1		1.1	2.3	3.5	3.8		ns
t <sub>PHL</sub>			0.5	3.8	3.9		1.3	2.1	3.3	3.6		
t <sub>PZH</sub>	OE	Y	0.8	5	6		1.1	2.5	4.5	5.3		ns
t <sub>PZL</sub>			0.8	5	5.4		1.4	2.7	4.4	4.9		
t <sub>PHZ</sub>	OE	Y	1.3	5.5	5.8		1.9	2.8	4.4	4.5		ns
t <sub>PLZ</sub>			1.2	4.7	4.8		1.8	2.9	4.4	4.4		

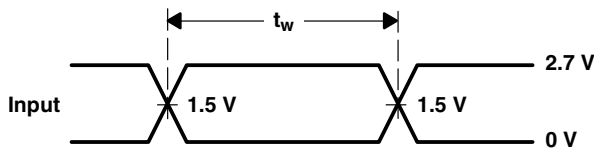
† All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

# PARAMETER MEASUREMENT INFORMATION

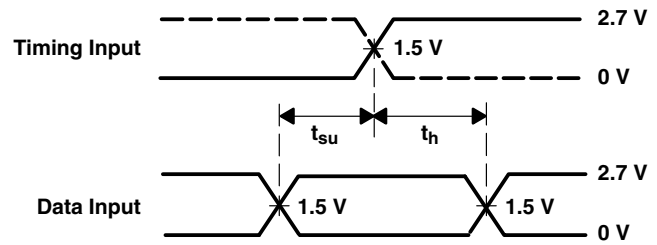


LOAD CIRCUIT

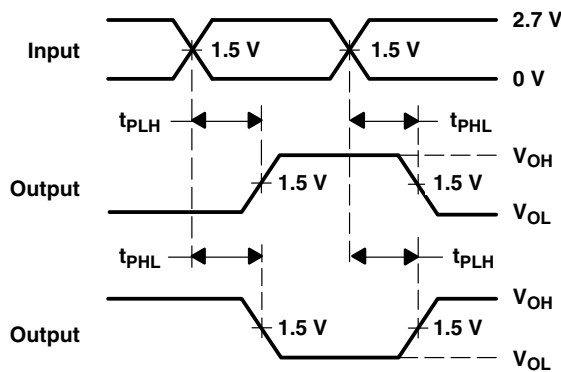
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND



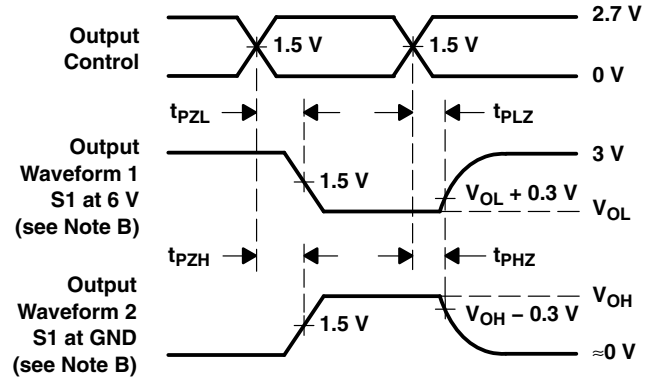
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - The outputs are measured one at a time with one transition per measurement.
  - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">5962-9584401Q2A</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9584401Q2A SNJ54LVTH 244AFK
<a href="#">5962-9584401QRA</a>	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9584401QR A SNJ54LVTH244AJ
<a href="#">5962-9584401QSA</a>	Active	Production	CFP (W)   20	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9584401QS A SNJ54LVTH244AW
<a href="#">5962-9584401V2A</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9584401V2A SNV54LVTH 244AFK
<a href="#">5962-9584401VRA</a>	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9584401VR A SNV54LVTH244AJ
<a href="#">5962-9584401VSA</a>	Active	Production	CFP (W)   20	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9584401VS A SNV54LVTH244AW
<a href="#">SN74LVTH244ADB</a>	Active	Production	SSOP (DB)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-	LXH244A
SN74LVTH244ADB.B	Active	Production	SSOP (DB)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
<a href="#">SN74LVTH244ADBR</a>	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
SN74LVTH244ADBR.B	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
SN74LVTH244ADBRE4	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
SN74LVTH244ADBRG4	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
<a href="#">SN74LVTH244ADW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A
SN74LVTH244ADW.B	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A
SN74LVTH244ADWE4	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A
SN74LVTH244ADWG4	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A
<a href="#">SN74LVTH244ADWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A
SN74LVTH244ADWR.B	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A
SN74LVTH244ADWRG4	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A



Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LVTH244ANS.B	Active	Production	SOP (NS)   20	40   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A
<a href="#">SN74LVTH244ANSR</a>	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A
SN74LVTH244ANSR.B	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A
SN74LVTH244ANSRG4.B	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH244A
<a href="#">SN74LVTH244APW</a>	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
SN74LVTH244APW.B	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
SN74LVTH244APWG4	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
<a href="#">SN74LVTH244APWR</a>	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	LXH244A
SN74LVTH244APWR.B	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
SN74LVTH244APWRE4	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
<a href="#">SN74LVTH244APWRG4</a>	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
SN74LVTH244APWRG4.B	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH244A
<a href="#">SN74LVTH244ARGYR</a>	Active	Production	VQFN (RGY)   20	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LXH244A
SN74LVTH244ARGYR.B	Active	Production	VQFN (RGY)   20	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LXH244A
<a href="#">SNJ54LVTH244AFK</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9584401Q2A SNJ54LVTH 244AFK
<a href="#">SNJ54LVTH244AJ</a>	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9584401QR A SNJ54LVTH244AJ
<a href="#">SNJ54LVTH244AW</a>	Active	Production	CFP (W)   20	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9584401QS A SNJ54LVTH244AW

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN54LVTH244A, SN54LVTH244A-SP, SN74LVTH244A :**

- Catalog : [SN74LVTH244A](#), [SN54LVTH244A](#)
- Enhanced Product : [SN74LVTH244A-EP](#), [SN74LVTH244A-EP](#)
- Military : [SN54LVTH244A](#)
- Space : [SN54LVTH244A-SP](#)

**NOTE: Qualified Version Definitions:**

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH244ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LVTH244ADWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74LVTH244ANSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LVTH244APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74LVTH244APWRG4	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74LVTH244ARGYR	VQFN	RGY	20	3000	330.0	12.4	3.8	4.8	1.6	8.0	12.0	Q1

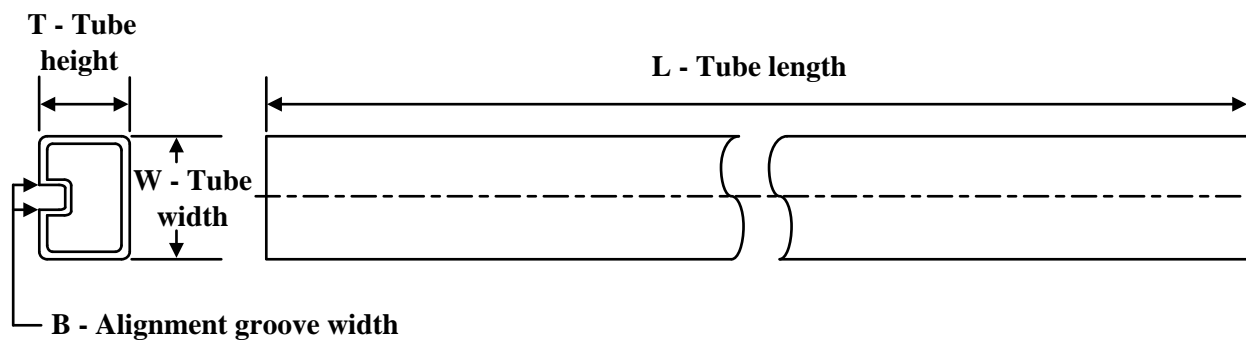
## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH244ADBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74LVTH244ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LVTH244ANSR	SOP	NS	20	2000	367.0	367.0	45.0
SN74LVTH244APWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74LVTH244APWRG4	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74LVTH244ARGYR	VQFN	RGY	20	3000	356.0	356.0	35.0

## TUBE



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9584401Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9584401V2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9584401VSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74LVTH244ADB	DB	SSOP	20	70	530	10.5	4000	4.1
SN74LVTH244ADB.B	DB	SSOP	20	70	530	10.5	4000	4.1
SN74LVTH244ADW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LVTH244ADW.B	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LVTH244ADWE4	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LVTH244ADWG4	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LVTH244ANS.B	NS	SOP	20	40	530	10.5	4000	4.1
SN74LVTH244APW	PW	TSSOP	20	70	530	10.2	3600	3.5
SN74LVTH244APW.B	PW	TSSOP	20	70	530	10.2	3600	3.5
SN74LVTH244APWG4	PW	TSSOP	20	70	530	10.2	3600	3.5
SNJ54LVTH244AFK	FK	LCCC	20	55	506.98	12.06	2030	NA

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## GENERIC PACKAGE VIEW

**RGY 20**

**VQFN - 1 mm max height**

3.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FGLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4225264/A



**VQFN - 1 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

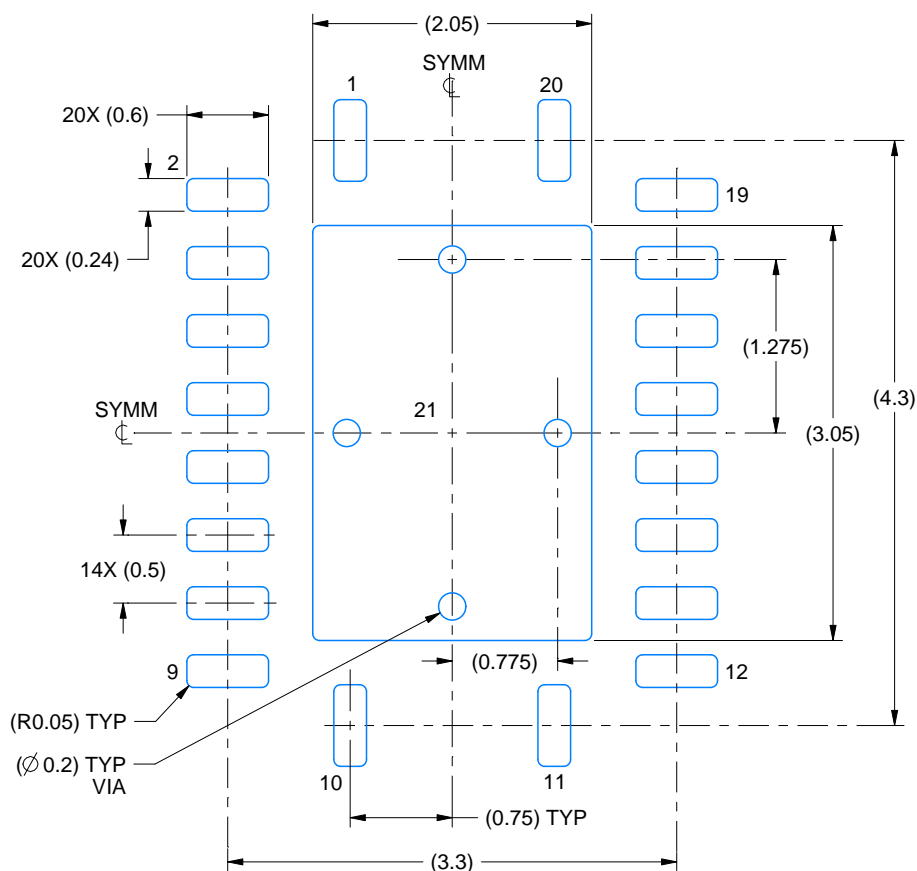
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



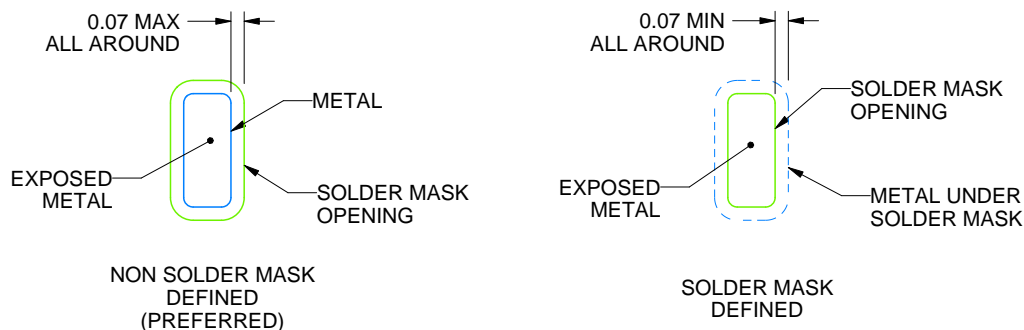
# RGY0020A

## VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



## SOLDER MASK DETAILS

4225320/A 09/2019

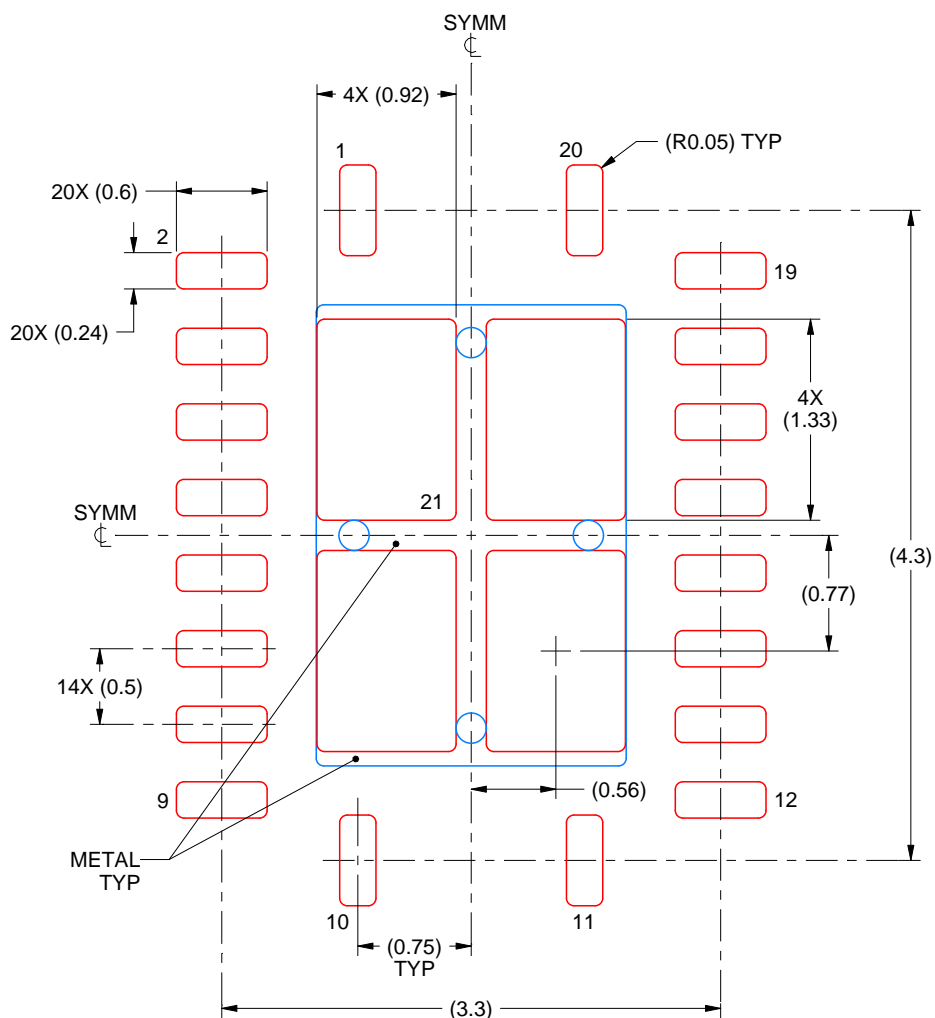
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

**RGY0020A**

### VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



## SOLDER PASTE EXAMPLE BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 21  
78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:20X

4225320/A 09/2019

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## GENERIC PACKAGE VIEW

**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\



4220724/A 05/2016

## NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

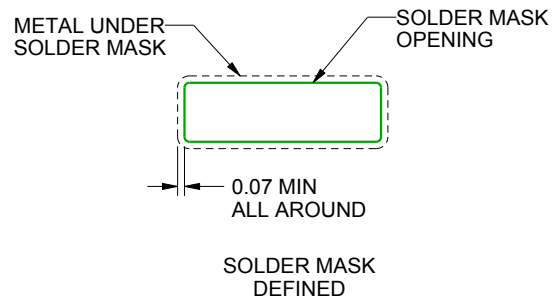
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

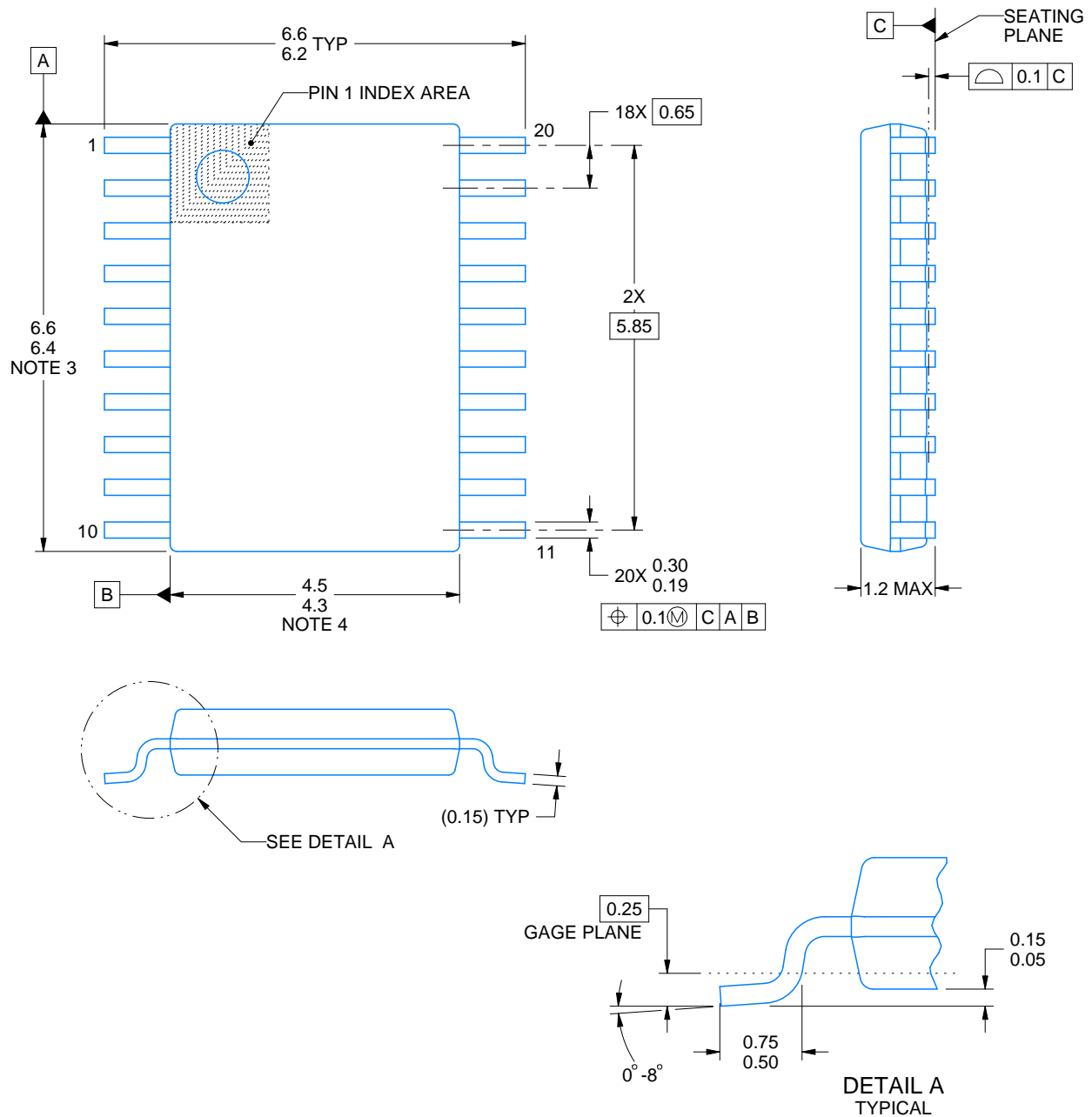
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20



4220206/A 02/2017

## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



# EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4214851/B 08/2019

## NOTES:

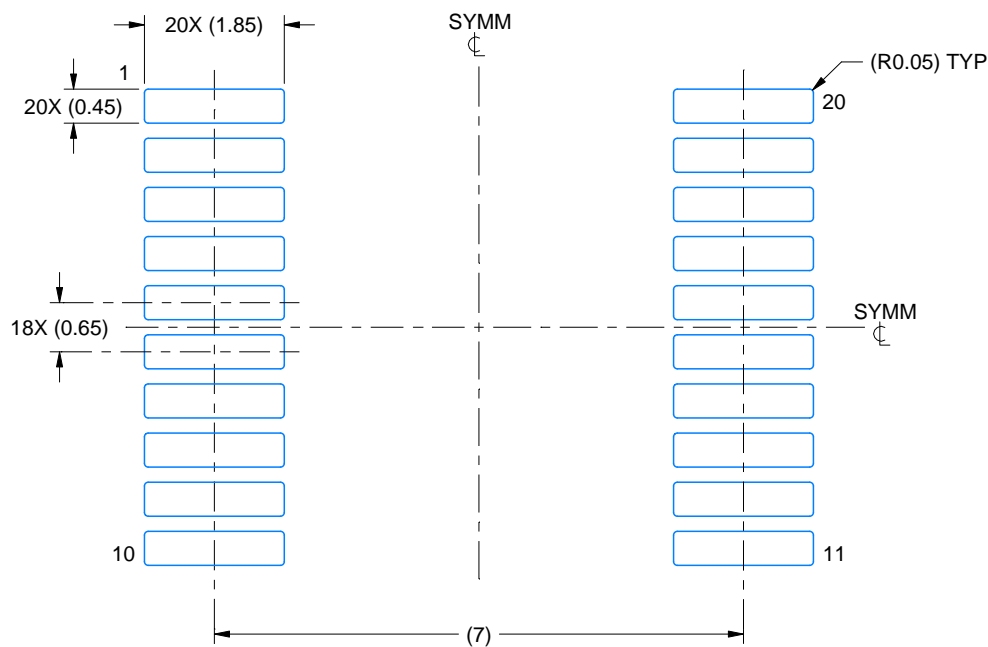
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

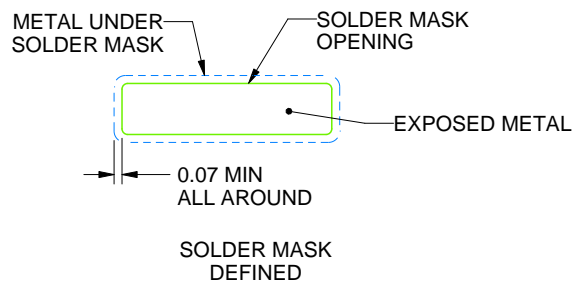
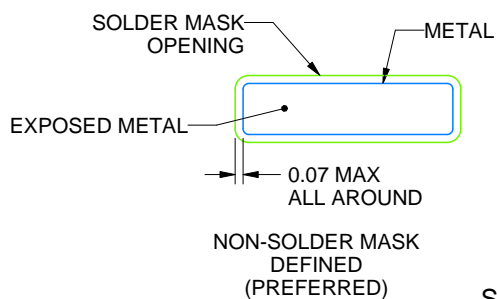
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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